



Product Change Notification

Date: Friday, November 12, 2010
PCN#: 140A00193-2
Subject: Encapsulation Material Change

Dear Customer,

In an effort to better communicate to you, our user community, we have implemented a e-mail version for our PCN process in addition to our PCN website. While you may receive a notification from us concerning a particular part or part numbers, it is not an indication that you use or have ordered these particular parts, but merely a communication to notify our user community as a whole. Please review your sales orders, POs, records, etc. to determine if this particular PCN impacts your activities or affects your business.

Microsemi Power and Microelectronics Group wishes to inform you of an End of Life of the Henkel/Loctite FP4651 liquid encapsulation material used on the following PBGA Standard Products:

W3H128M72E-XSBX	W3E32M64SA-XBX	W332M64V-XSBX
W3H128M72E-XNBX	W3E16M72S-XBX	W332M64V-XBX
W3H128M72ER-XNBX	W3E16M64S-XBX	WEDPN16M72VR-XB2X
W3H64M72E-XSBX	W3E64M16S-XSBX	WEDPN16M64VR-XB2X
W3H64M64E-XSBX	W3E64M16S-XNBX	W72M64VB-XBX
W3H32M72E-XSBX	WEDPN16M72X-XB2X	W78M32VP-XBX
W3H32M72E-XSB2X	WEDPN16M64X-XB2X	W78M64VP-XSBX
W3H32M64E-XSBX	WEDPN8M72X-XB2X	W764M32V-XSBX
W3E64M72S-XSBX	WEDPN8M64X-XB2X	WED2DL32512V
W3E32M72S-XSBX	WEDPN4M72X-XB2X	WEDPY256K72V-XBX
W3E32M72SR-XSBX	WEDPN4M64X-XBX	WEDPZ512K72V-XBX
W3E32M72S-XBX	W364M72V-XSBX	WEDPZ512K72S-XBX
W3E32M64S-XSBX	W332M72V-XSBX	WED3DL3216V
W3E32M64S-XBX	W332M72V-XBX	C50662
C50657	C50663	

Henkel/Loctite has offered a last time buy date of April 2011 for the FP4651 material. Microsemi is evaluating alternate sources and will be scheduling qualification testing once a material is selected.

If you have any questions, please contact the factory.

As technology moves at a much faster pace, advanced embedded electronic components play a more strategic role. Constant changes and advancements in technology mandate that we anticipate changes and directions in technology for the benefit of our customers. As one of the pioneers in advanced semiconductor packaging and high-density memory solutions, we stand ready to assist you in managing this evolution of technology. If we can provide any additional assistance, please contact us at 602.437.1520 or complete a contact form at www.whiteedc.com/contact_us.html.

Best regards,
Microsemi Power and Microelectronics Group Engineering